AMENDMENTS TO THE CLAIMS

Please amend the claims as follows.

1. (Currently Amended) A method for producing an electrical device made up by a first object for bonding including a first electrode and a second object for bonding including a second electrode to be connected to said first electrode, by bonding said first object for bonding and said second object for bonding to each other, comprising the steps of

arranging an adhesive, mainly containing a thermosetting resin and a silane coupling agent as a first curing agent, at least on said first electrode, to form an adhesive layer, wherein electrically conductive particles are added to said adhesive from the outset;

arranging a second curing agent, reacted with said first curing agent by heating to polymerize said thermosetting resin, at least on said second electrode, to ~~from~~ form a layer of the second curing agent, said second curing agent being mainly composed of one [[of]] or both [[or]] of an ~~metal~~ aluminum chelate and an ~~metal~~ aluminum alcoholate;

positioning said first and second electrodes in register with each other;

tightly contacting said adhesive on said first object for bonding with said second curing agent on said second object for bonding; and

thrusting and heating said first and second objects against each other ~~to react said first and second curing agents~~ for bonding to develop a curing component by reaction of said silane coupling agent as a main component of said first curing agent and one or both of said aluminum chelate and said aluminum alcoholate of the second curing agent ~~against each other~~ and for interconnecting said first and second electrodes through said electrically conductive particles and allowing said thermosetting resin to be polymerized with said curing component by heating.

2. (Cancelled)

3. (Cancelled)

4. (Currently Amended) The method for producing an electrical device according to claim 1 wherein said ~~metal~~ aluminum chelate is one of ethyl acetoacetate aluminum diisopropylate, alkyl acetoacetate aluminum diisopropylate and aluminum monoacetyl acetonate bis ethylacetroacetate.

5. (Previously Presented) The method for producing an electrical device according to claim 1 wherein a compound represented by the following formula:

is used as said silane coupling agent, wherein at least one of the substituents X^1 to X^4 is an alkoxy group and at least one of the substituents different from the alkoxy group includes an epoxy ring.

6. (Previously Presented) The method for producing an electrical device according to claim 1 wherein, as said silane coupling agent, a compound shown by the formula:

is used, wherein at least one of the substituents X^1 to X^4 is an alkoxy group and at least one of the substituents different from the alkoxy group includes an epoxy ring, and where said substituent including the epoxy ring is a glycidyl group.

7. (Previously Presented) The method of producing an electrical device according to claim 1 wherein said thermosetting resin forming said adhesive layer is an epoxy resin and wherein said second curing agent layer further contains an epoxy resin.

8. (Previously Presented) The method of producing an electrical device according to claim 1 wherein said second curing layer is formed by spraying said second curing agent liquid at

ambient temperature or a liquid dispersion containing said second curing agent dispersed therein.

9. (Previously Presented) The method of producing an electrical device according to claim 1 wherein said second curing layer is formed by coating said second curing agent liquid at ambient temperature or a liquid dispersion containing said second curing agent dispersed therein.